

#### Wire Wound Chip Inductors

SWI1008HQ Series



#### INTRODUCTION

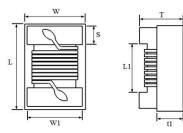
The SWI series are wire wound chip inductors widely used in the communication applications such as cellular phones, cable modem, ADSL, repeaters, Bluetooth, and other electronic devices. The wire wound inductors advance in higher self resonate frequency, better Q factor, and much more stable performance. The HQ type offer higher Q factor and the current handling has also been improved with significantly lower DCR value. Precious tolerance of 2% is available.

#### **FEATURES**

- > Operating temperature -40 to +125°C for ceramic series.
- Excellent solderability and resistance to soldering heat.
- Suitable for reflow soldering.
- ➤ High reliability and easy surface mount assembly.
- Wide range of inductance values are available for flexible needs.

#### PART NUMBER

- 1 Product Type
- 2 Chip Dimension



Size	Length (L)	Width (W)	Thickness (T)	Terminal (S)	$(t_1)$
(inch)	(inch)	(inch)	(inch)	(inch)	(Ref.)
mm	mm	mm	mm	mm	mm
SWI 1008	$(0.098 \pm 0.008)$	$(0.080 \pm 0.008)$	$(0.063 \pm 0.008)$	$(0.020 \pm 0.004)$	0.70
2520	$2.60 \pm 0.20$	$2.10 \pm 0.20$	$1.70 \pm 0.20$	$0.50 \pm 0.10$	0.70

- 3 Material Type HQ: High Q type
- 4 Inductance Value 10N = 10nH R10 = 100nH
- 5 Tolerance  $G = \pm 2\%$   $J = \pm 5\%$   $K = \pm 10\%$
- 6 Internal Code

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# 1 Scope

This specification applies to fixed inductors of the following types used in electronic equipment:

\*HQ Type : For lower inductance with high Q factor at high frequency and

stable circuit requirement.

#### 2 Construction

\*Configuration

& Dimension: Please refer to the attached figures and tables.

\*Terminals : Consist of Ag alloy followed by Nickel, then Au platting for easier

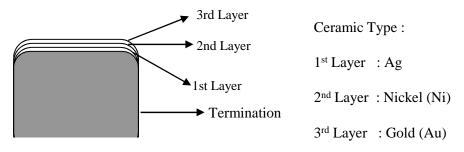
soldering.

#### 3 Operating Temperature Range

Operating Temperature Range is the scope of ambient temperature at which the inductor can be operated continuously at rated current.

\*Temp. Range : Ceramic material : -40°C ~ +125°C

## 4 Ingredient of terminals electrode



#### 5 Characteristics

#### **Standard Atmospheric Conditions**

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows:

Ambient Temperature :  $25^{\circ}C \pm 2^{\circ}C$ 

Relative Humidity : 60% to 70%

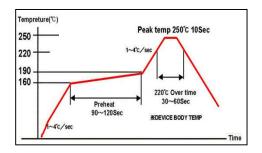
Air Pressure : 86Kpa to 106Kpa



Temperature Profile

## 1 Reflow Temperature Profile

(Temperature of the mounted parts surface on the printed circuit board)



Recommended Peak Temperature: 250°C Max

250°C up /within 10secs

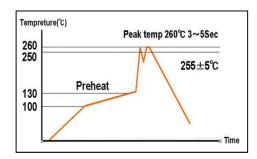
Max. Reflow temperature: 260°C

Gradient of temperature rise : av 1-4°C/sec Preheat : 160-190°C/within 90-120secs

220°C up /within 30-60secs

Composition of solder Sn-3Ag-0.5Cu

# 2 Dip Temperature



Solder bathtub temperature: 260°C max

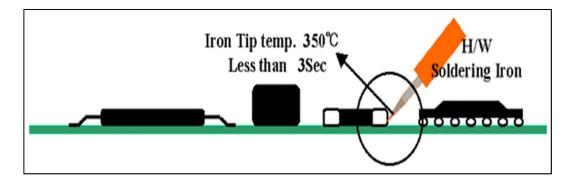
within 5secs.

Preheating temperature: 100~130°C

deposit solder temperature.

Composition of solder Sn-3Ag-0.5Cu

3 Soldering iron tip temperature : 350°C max / within 3 seconds.





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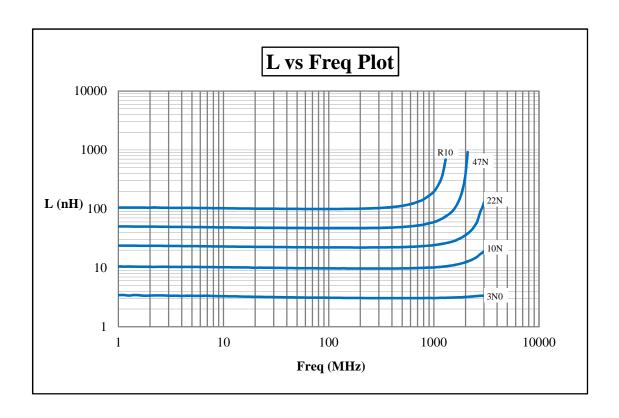
Part No.	Inductance <sup>1</sup> (nH)	Tolerance	Q <sup>2</sup> Min	S.R.F. <sup>3</sup> Min (MHz)	RDC <sup>4</sup> Max (Ω)	IDC <sup>5</sup> Max (mA)	Marking
SWI1008HQ 3N0 □-□□	3.0 @ 50MHz	K, J	70 @ 1500MHz	8100	0.04	1600	3N0
SWI1008HQ 7N8 □-□□	7.8 @ 50MHz	K, J	75 @ 1500MHz	3800	0.05	1600	7N8
SWI1008HQ 10N □-□□	10 @ 50MHz	K, J	60 @ 500MHz	3600	0.08	1300	10N
SWI1008HQ 12N □-□□	12 @ 50MHz	K, J, G	70 @ 500MHz	2800	0.06	1500	12N
SWI1008HQ 18N □-□□	18 @ 50MHz	K, J, G	62 @ 350MHz	2700	0.08	1400	18N
SWI1008HQ 22N □-□□	22 @ 50MHz	K, J, G	62 @ 350MHz	2050	0.07	1400	22N
SWI1008HQ 33N □-□□	33 @ 50MHz	K, J, G	75 @ 350MHz	1700	0.09	1300	33N
SWI1008HQ 39N □-□□	39 @ 50MHz	K, J, G	75 @ 350MHz	1300	0.09	1300	39N
SWI1008HQ 47N □-□□	47 @ 50MHz	K, J, G	75 @ 350MHz	1450	0.12	1200	47N
SWI1008HQ 56N □-□□	56 @ 50MHz	K, J, G	75 @ 350MHz	1230	0.12	1200	56N
SWI1008HQ 68N □-□□	68 @ 50MHz	K, J, G	80 @ 350MHz	1150	0.13	1000	68N
SWI1008HQ 82N □-□□	82 @ 50MHz	K, J, G	80 @ 350MHz	1060	0.16	1000	82N
SWI1008HQ R10	100 @ 50MHz	K, J, G	62 @ 350MHz	820	0.16	1000	R10

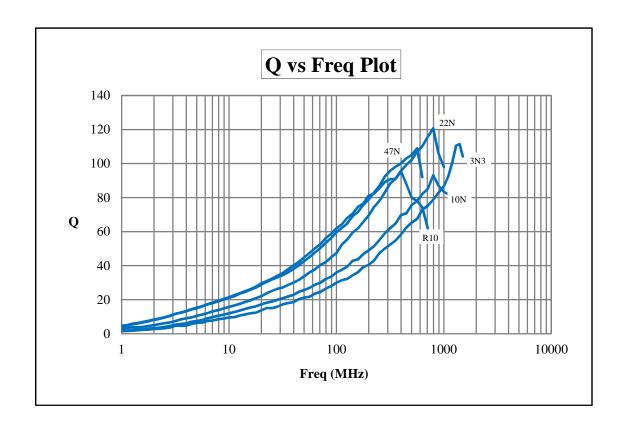
- 1. Inductance is measured in HP-4287A RF LCR meter with HP-16193 fixture.
- 2. Q is measured in HP-4287A RF LCR meter with HP-16193 fixture.
- 3. SRF is measured in ENA E5071B network analyzer or equivalent.
- 4. RDC is measured in HP-4338B milliohmeter or equivalent.
- 5. For 15 °C Rise.

#### Remarks:

 $\overline{\text{Unit weight}} = 0.025g \text{ (for ref.)}$ 







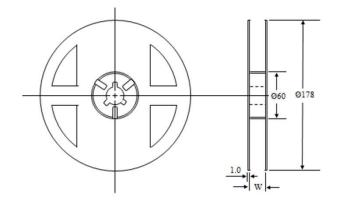


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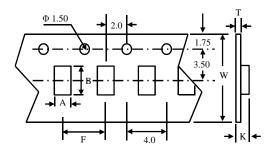
Inductance and Tolerance
Resistance   Characteristics   Characteristics   Characteristics   Characteristics   Characteristics   Dieketric   Measured at 500V AC between inductor terminals and center of case.   No damage occurs when the test voltage is applied.   Woltage for a maximum of 1 minute.   Yoltage for Yoltage for Appearance:   Yoltage for Yo
Insulation   Measured at 100V DC between   1000 mega ohms minimum   Resistance   Inductor terminals and center of case.   No damage occurs when the test voltage is applied.
Resistance   Inductor terminals and center of case.   No damage occurs when the test voltage is applied.
Characteristics         Dielectric Withstanding Voltage         Measured at 500V AC between inductor terminals and center of case for a maximum of 1 minute.         No damage occurs when the test voltage is applied.           Temperature Coefficient of Inductance (TCL)         Over -40°C to +85°C at frequency specified in Product Table.         +25 to 500 ppm°C         TCL = L1 - L2 x 10 <sup>6</sup> (ppm /°C) L1(T1-T2)           Component Adhesion (Push Test)         The component shall be reflow soldered onto a P.C. Board (240°C ± 5°C for 20 seconds). Then a dynometer force gauge shall be applied to any side of the component.         Minimum 1Kg         Minimum 1Kg           Mechanical Characteristics           Thermal Shock Test         Each cycle shall consist of 30 minutes at -40°C followed by 30 minutes at +85°C with a 5 minutes transition time between temperature extremes. Test duration is 10 cycles.         Change In Inductance: No more than 10% Change In Appearance: Without distinct damage           Solderability         Dip pads in flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 seconds.         A minimum of 80% of the metalized area must be covered with solder.           Resistance to Soldering Heat         Dip the components into flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 ± 2 seconds.         Change In Inductance: No more than 10% Change In Inductance: No more than 15%           Vibration         Inductors shall be randomly vibrated at amplitude of 1.5mm and frequency of 10-55Hz : 0.04G/Hz for a minimum of 15 minutes per axis for each of the three
Withstanding Voltage for a maximum of 1 minute.  Temperature Coefficient of Inductance (TCL) Inductance (TCL)  Component Adhesion (Push Test)  The na dynometer force gauge shall be applied to any side of the component.  Thermal Shock Test Feach cycle shall consist of 30 minutes at +40°C Test followed by 30 minutes at +85°C with a 5 minutes transition time between temperature extremes. Test duration is 10 cycles.  Soklerability  Soklerability  Resistance to Soklering Heat  Vibration (Random)  Cold Temperature Storage  Withstanding frequency specified in Product Table. The component shall be reflow soklered onto a dather transition time between temperature extremes. Test duration is 10 cycles.  Change In Inductance: No more than 5% Change In Q: No more than 10% Change In Q: No more than 10% Change In Appearance: Without distinct damage A minimum of 80% of the metalized area must be covered with solder. No more than 10% Change In Q: No more than 5% Change In Appearance: Without distinct damage A minimum of 80% of the metalized area must be covered with solder. No more than 5% Change In Appearance: Without distinct damage Without damage Without damage Without damage Without damage Without damage Without
Voltage
Temperature Coefficient of Inductance (TCL)  Component Adhesion (Push Test)  The inductor shall be reflow soldered onto a P.C. Board (240°C ± 5°C for 20 seconds).  Then a dynometer force gauge shall be applied to any side of the component.  The inductor shall be dropped two times on the concrete floor or the vinyl tile from 1M naturally.  Thermal Shock Test Followed by 30 minutes at +40°C Test followed by 30 minutes at +85°C with a 5 minutes transition time between temperature extremes. Test duration is 10 cycles.  Solderability Dip pads in flux and dip into solder pot containing lead free solder at 240°C ± 5°C for 5 ± 2 seconds.  Vibration (Random) Vibration Cold Temperature Storage  Temperature Coefficient of frequency specified in Product Table.  The roductor shall be reflow soldered onto a P.C. Board (240°C ± 5°C for 5 to 20 seconds).  The component shall be reflow soldered onto a P.C. Board (240°C ± 5°C for 20 seconds).  Then a dynometer force gauge shall be applied to any side of the component.  Change In Inductance: No more than 10% Change In Appearance: Without distinct damage  Change In Inductance: No more than 5% Change In Inductance: No more than 5% Change In Q: No more than 10% Change In Inductance: No more than 10% Change In Appearance: Without distinct damage  Change In Appearance: No more than 10% Change In Appearance: Without distinct damage  The product of the components into flux and dip into solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Cold Temperature Storage  Cold Temperature Storage  Test duration is Product Table.  The components shall be reflow solder on the concrete on the concrete shall be applied to any side of the components of 30 minutes at -40°C Change In Inductance: No more than 5% Change In Appearance: Without distinct damage  Change In Appearance: Without distinct damage
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Inductance (TCL)   The component shall be reflow soldered onto a Adhesion   P.C. Board ( 240°C ± 5°C for 20 seconds ).
Component Adhesion (Push Test)  The component shall be reflow soldered onto a P.C. Board ( 240°C ± 5°C for 20 seconds ). Then a dynometer force gauge shall be applied to any side of the component.  The inductor shall be dropped two times on the concrete floor or the vinyl tile from 1M naturally. Thermal Shock Test Followed by 30 minutes at +85°C with a 5 minutes transition time between temperature extremes. Test duration is 10 cycles.  Solderability Dip pads in flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 seconds.  Resistance to Soldering Heat Titos office components into flux and dip into solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration (Random) Tinductors shall be randomly vibrated at amplitude of 1.5mm and frequency of 10-55Hz: 0.04G/Hz for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage  The components shall be reflow soldered onto a P.C. Board (240°C ± 5°C for 20 seconds).  Then a dynometer force gauge shall be applied to any side of the components.  Change In Inductance: No more than 10% Change In Appearance: No more than 5% Change In Rumant of 10 minutes per axis for each of the three axes.  Cold Temperature Storage  The inductor shall be dropped two times on the connected to the components.  Change In Q: No more than 10% Change In Appearance: Without distinct damage  Without distinct damage
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Mechanical Characteristics  Drop Test The inductor shall be dropped two times on the concrete floor or the vinyl tile from 1M naturally. Thermal Shock Test followed by 30 minutes at +85°C with a 5 minutes transition time between temperature extremes. Test duration is 10 cycles.  Solderability Dip pads in flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 seconds.  Resistance to Soldering Heat Solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration (Random) Of 1.5mm and frequency of 10-55Hz: 0.04G/Hz for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage  The inductor shall be dropped two times on the concrete floor or the vinyl tile from 1M naturally. Change In Inductance: Without distinct damage A minimum of 80% of the metalized area must be covered with solder. Change In Inductance: No more than 5% Change In Inductance: No more than 5% Change In Q: No more than 10% Change In Q: No more than 10% Change In Q: No more than 10% Change In Appearance: Without distinct damage  Without distinct damage
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Concrete floor or the vinyl tile from 1M naturally.  Thermal Shock Test  Followed by 30 minutes at +48°C with a 5 minutes transition time between temperature extremes. Test duration is 10 cycles.  Solderability  Dip pads in flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 seconds.  Resistance to Soldering Heat  Tinto solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration  Inductors shall be randomly vibrated at amplitude (Random)  Total Temperature Storage  Concrete floor or the vinyl tile from 1M naturally. Change In Q: No more than 10% Change In Appearance: Without distinct damage  A minimum of 80% of the metalized area must be covered with solder. Change In Inductance: No more than 5% Change In Inductance: No more than 10% Change In Q: No more than 10% Change In Appearance: Without distinct damage  Change In Q: No more than 10% Change In Q: No more than 10% Change In Q: Without distinct damage
Test followed by 30 minutes at +85°C with a 5 minutes transition time between temperature extremes.  Test duration is 10 cycles.  Solderability Dip pads in flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 seconds.  Resistance to Dip the components into flux and dip into solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration Inductors shall be randomly vibrated at amplitude (Random) of 1.5mm and frequency of 10-55Hz : 0.04G/Hz for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage of -40°C ± 2°C for 1000hrs (+48 -0 hrs.)
transition time between temperature extremes.  Test duration is 10 cycles.  Dip pads in flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 seconds.  Resistance to Dip the components into flux and dip Soldering Heat into solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration (Random)  Of 1.5mm and frequency of 10-55Hz: 0.04G/Hz for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage  The three axes are the transition time between temperature extremes.  Change In Appearance: Without distinct damage  A minimum of 80% of the metalized area must be covered with solder.  Change In Inductance: No more than 5% Change In Q: No more than 10% Change In Appearance: Without distinct damage
Test duration is 10 cycles.  Dip pads in flux and dip in solder pot containing lead free solder at 240°C ± 5°C for 5 seconds.  Resistance to Dip the components into flux and dip Soldering Heat Into solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration Inductors shall be randomly vibrated at amplitude (Random) Of 1.5mm and frequency of 10-55Hz: 0.04G/Hz for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage  Test duration is 10 cycles. Without distinct damage  A minimum of 80% of the metalized area must be covered with solder.  Change In Inductance: No more than 5% Change In Q: No more than 10% Change In Appearance: Without distinct damage
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lead free solder at 240°C ± 5°C for 5 seconds.  Resistance to Soldering Heat into solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration (Random) Inductors shall be randomly vibrated at amplitude (Random) Of 1.5mm and frequency of 10-55Hz : 0.04G/Hz for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage  Resistance to Dip the components into flux and dip Change In Inductance: No more than 10% Change In Q: Without distinct damage Without distinct damage
Resistance to Soldering Heat into solder pot containing lead free solder at 260°C ± 5°C for 5 ± 2 seconds.  Vibration (Random) Inductors shall be randomly vibrated at amplitude (Random) of 1.5mm and frequency of 10-55Hz : 0.04G/Hz for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage  Dip the components into flux and dip No more than 5% Change In Q: No more than 10% Change In Appearance: Without distinct damage
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Vibration Inductors shall be randomly vibrated at amplitude (Random) of 1.5mm and frequency of 10-55Hz : 0.04G/Hz (Change In Appearance: without distinct damage the three axes.  Cold Temperature Storage of -40°C ± 2°C for 1000hrs (+48 -0 hrs.)
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for a minimum of 15 minutes per axis for each of the three axes.  Cold Temperature Storage  Of -40°C ± 2°C for 1000hrs (+48 -0 hrs.)  Without distinct damage  Without distinct damage
the three axes.  Cold Temperature Inductors shall be stored at temperature Storage  of -40°C ± 2°C for 1000hrs (+48 -0 hrs.)
Storage of $-40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 1000hrs (+48 -0 hrs.)
There is directors shall be earliered to see a 1 and
Then inductors shall be subjected to standard
Endurance atmospheric conditions for 1 hour.
Characteristics After that, measurement shall be made.
High Temperature Inductors shall be stored at temperature
Storage of $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for $1000\text{hrs} (+48 - 0 \text{ hrs.})$
Then inductors shall be subjected to standard
atmospheric conditions for 1 hour.
After that, measurement shall be made.
Moisture Inductors shall be stored in the chamber at 45°C Inductors shall not have a
Resistance at 90-95 R.H. for 1000 hours. Then inductors are shorted or open winding.
to be tested after 2 hours at room temperature.  High Temperature Inductors shall be stored in the chamber at +85°C
with Loaded for 1000 hours with rated current applied.
Inductors shall be tested at the beginning of test at
500 hours and 1000 hours. Then inductors are to
be tested after 1 hour at room temperature.

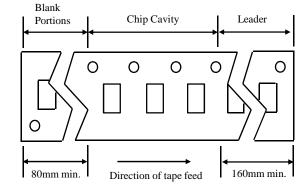


Туре	Pcs/Reel
SWI1008HQ	2,000



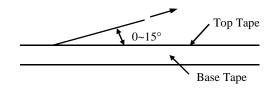
Туре	Ch Cav	ip vity	Insert Pitch	Taj	pe Thickn	iess
	A	В	F	K	T	W
SWI1008HQ	2.20	2.83	4.00	1.75	0.22	8.00





#### Top Tape Strength

The top tape requires a peel-off force of  $0.2\ to\ 0.7N$  in the direction of the arrow as illustrated below.



#### Dimensions (unit: m/m)

Туре	A	В	C
SWI1008HQ	3.00	1.20	2.20

#### Recommended Pattern

